STGB20V60DF, STGP20V60DF, STGW20V60DF, STGWT20V60DF

600 V, 20 A very high speed trench gate field-stop IGBT

Datasheet - production data

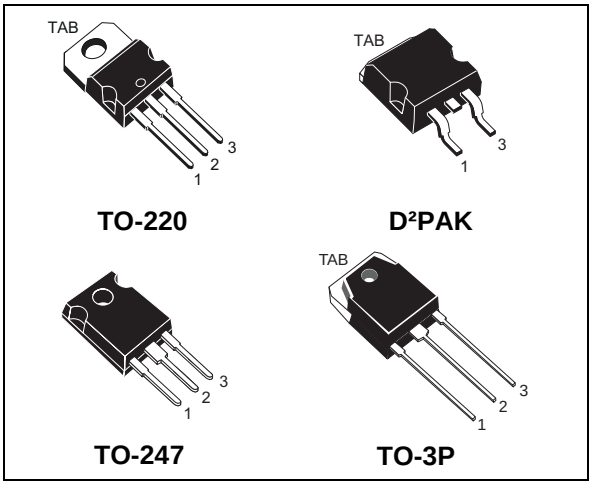
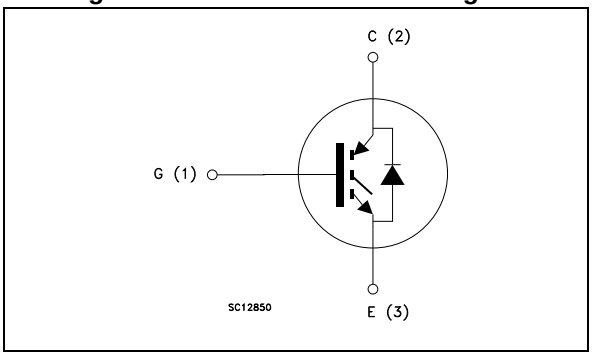


Figure 1. Internal schematic diagram



Features

- Maximum junction temperature: T_J = 175 °C
- Very high speed switching series
- Tail-less switching off
- Low saturation voltage: $V_{CE(sat)}$ = 1.8 V (typ.) @ I_C = 20 A
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- Very fast soft recovery antiparallel diode
- Lead free package

Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- Power factor correction
- Very high frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate and field stop structure. The device is part of the "V" series of IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, a positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1. Device summary

Order code	Marking	Package	Packaging
STGB20V60DF	GB20V60DF	D²PAK	Tape and reel
STGP20V60DF	GP20V60DF	TO-220	Tube
STGW20V60DF	GW20V60DF	TO-247	Tube
STGWT20V60DF	GWT20V60DF	TO-3P	Tube

Contents

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage (V_{GE} = 0)	600	V
I_C	Continuous collector current at T_C = 25 °C	40	A
I_C	Continuous collector current at T_C = 100 °C	20	A
I_{CP}(1)	Pulsed collector current	80	A
V_{GE}	Gate-emitter voltage	±20	V
I_F	Continuous forward current at T_C = 25 °C	40	A
I_F	Continuous forward current at T_C = 100 °C	20	A
$I_{FP(1)}$	Pulsed forward current	80	A
P_{TOT}	Total dissipation at T_C = 25 °C	167	W
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature	- 55 to 175	°C

1. Pulse width limited by maximum junction temperature and turn-off within RBSOA

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.9	°C/W
R_{thJC}	Thermal resistance junction-case diode	2.08	°C/W
R_{thJA}	Thermal resistance junction-ambient	50	°C/W

2 Electrical characteristics

T_J = 25 °C unless otherwise specified.

Table 4. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage (V_{GE} = 0)	I_C = 2 mA	600			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{GE} = 15 V, I_C = 20 A		1.8	2.2	V
		V_{GE} = 15 V, I_C = 20 A T_J = 125 °C		2.15		
		V_{GE} = 15 V, I_C = 20 A T_J = 175 °C		2.3		
V_F	Forward on-voltage	I_F = 20 A		1.7	2.2	V
		I_F = 20 A T_J = 125 °C		1.55		V
		I_F = 20 A T_J = 175 °C		1.3		V
$V_{GE(th)}$	Gate threshold voltage	V_{CE} = V_{GE}, I_C = 1 mA	5	6	7	V
I_{CES}	Collector cut-off current (V_{GE} = 0)	V_{CE} = 600 V			25	µA
I_{GES}	Gate-emitter leakage current (V_{CE} = 0)	V_{GE} = ± 20 V			250	nA

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	V_{CE} = 25 V, f = 1 MHz, V_{GE} = 0	-	2800	-	pF
C_{oes}	Output capacitance		-	110	-	pF
C_{res}	Reverse transfer capacitance		-	64	-	pF
Q_g	Total gate charge	V_{CC} = 480 V, I_C = 20 A, V_{GE} = 15 V, see *Figure 29*	-	116	-	nC
Q_{ge}	Gate-emitter charge		-	24	-	nC
Q_{gc}	Gate-collector charge		-	50	-	nC

Table 6. IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 20 A, V_{GE} = 15 V, *see Figure 28*	-	38	-	ns
t_r	Current rise time		-	10	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1556	-	A/µs
$t_{d(off)}$	Turn-off delay time		-	149	-	ns
t_f	Current fall time		-	15	-	ns
E_{on} (1)	Turn-on switching losses		-	200	-	µJ
E_{off} (2)	Turn-off switching losses		-	130	-	µJ
E_{ts}	Total switching losses		-	330	-	µJ
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 20 A, di/dt = 1000 A/µs, V_{GE} = 15 V, T_J = 175 °C, see *Figure 28*	-	37	-	ns
t_r	Current rise time		-	12	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1340	-	A/µs
$t_{d(off)}$	Turn-off delay time		-	150	-	ns
t_f	Current fall time		-	23	-	ns
E_{on} (1)	Turn-on switching losses		-	430	-	µJ
E_{off} (2)	Turn-off switching losses		-	210	-	µJ
E_{ts}	Total switching losses		-	640	-	µJ

1. Energy losses include reverse recovery of the diode.
2. Turn-off losses include also the tail of the collector current.

Table 7. Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	I_F = 20 A, V_R = 400 V, V_{GE} = 15 V, see *Figure 28* di/dt = 1000 A/µs	-	40	-	ns
Q_{rr}	Reverse recovery charge		-	320	-	nC
I_{rrm}	Reverse recovery current		-	16	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	910	-	A/µs
E_{rr}	Reverse recovery energy		-	115	-	µJ
t_{rr}	Reverse recovery time	I_F = 20 A, V_R = 400 V, V_{GE} = 15 V, T_J = 175 °C, see *Figure 28* di/dt = 1000 A/µs	-	72	-	ns
Q_{rr}	Reverse recovery charge		-	930	-	nC
I_{rrm}	Reverse recovery current		-	26	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	530	-	A/µs
E_{rr}	Reverse recovery energy		-	307	-	µJ

2.1 Electrical characteristics (curves)

Figure 2. Power dissipation vs. case temperature

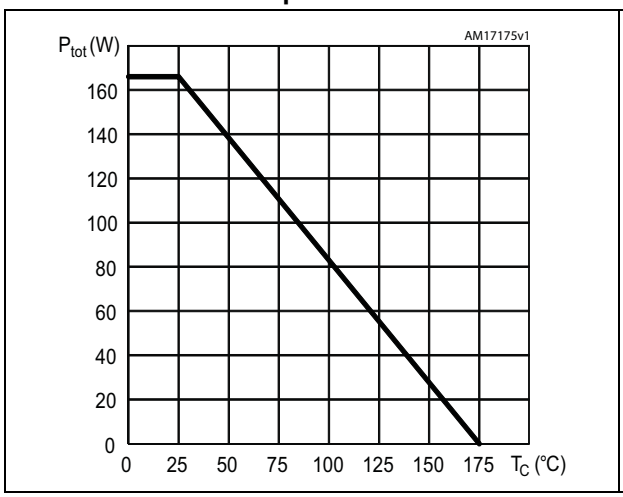


Figure 3. Collector current vs. case temperature

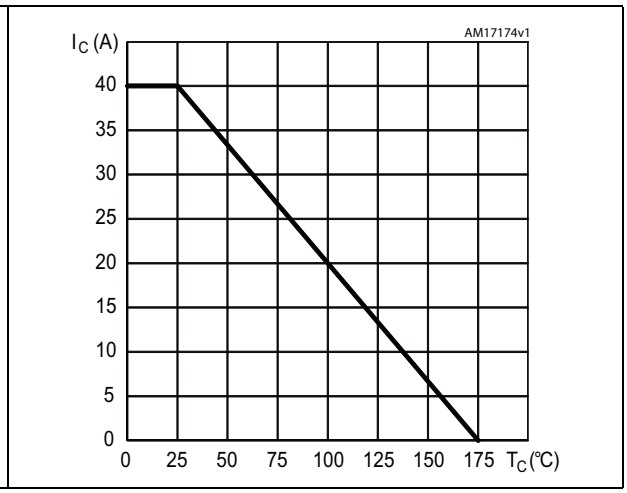


Figure 4. Output characteristics (T_J = 25 °C)

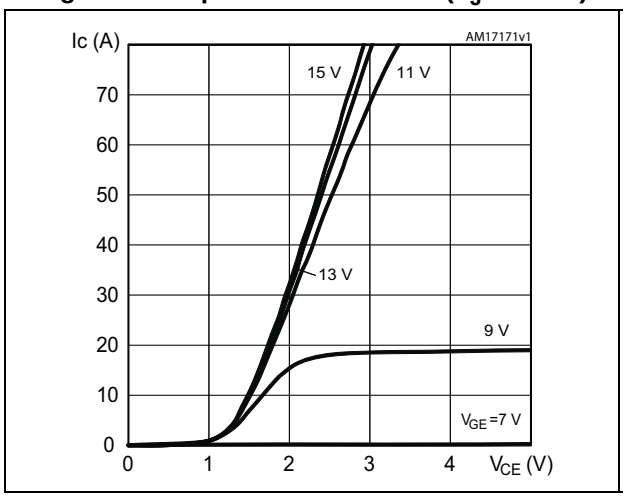


Figure 5. Output characteristics (T_J = 175 °C)

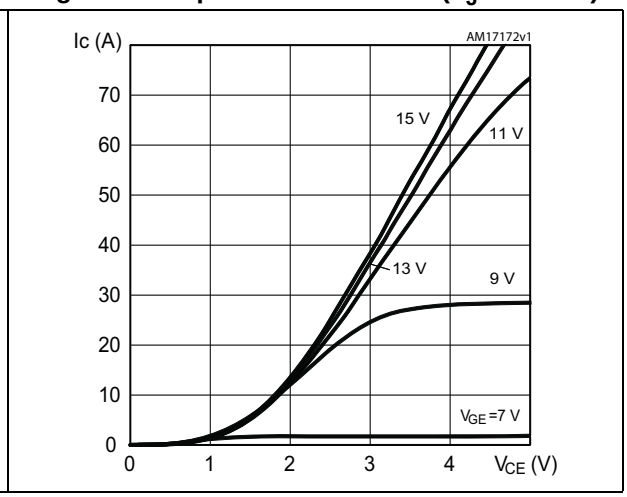


Figure 6. $V_{CE(SAT)}$ vs. junction temperature

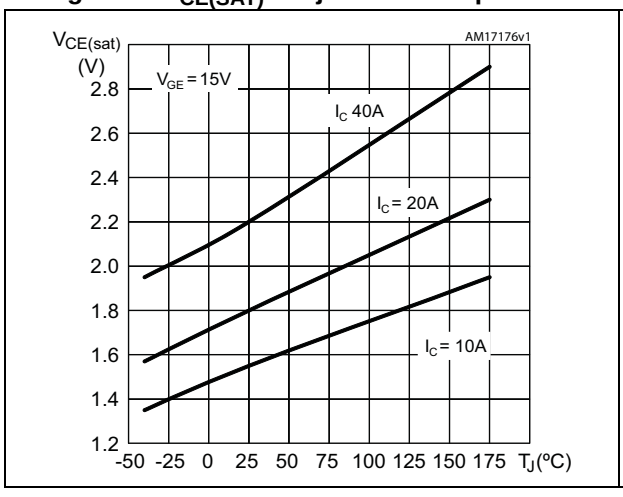


Figure 7. $V_{CE(SAT)}$ vs. collector current

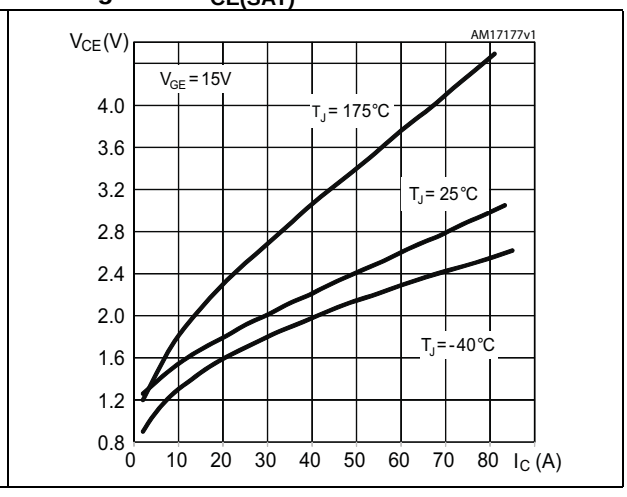


Figure 8. Collector current vs. switching frequency

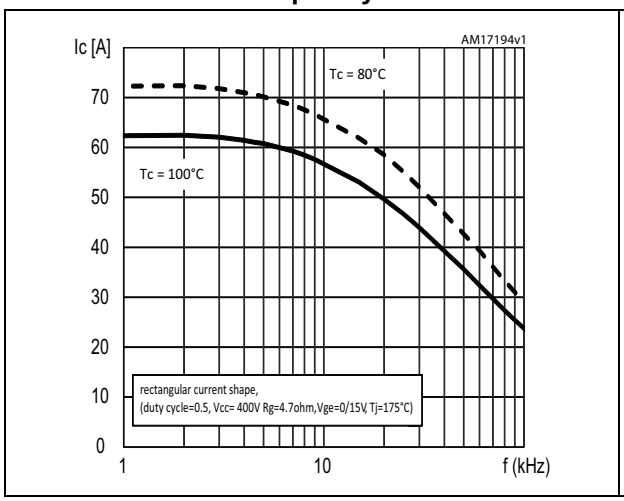


Figure 9. Forward bias safe operating area

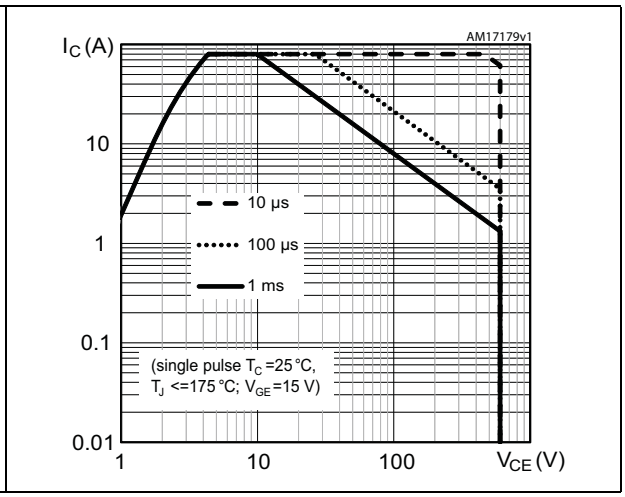


Figure 10. Transfer characteristics

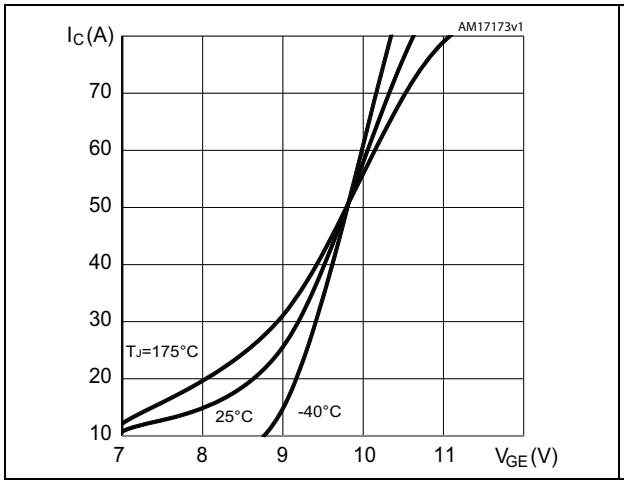


Figure 11. Diode V_F vs. forward current

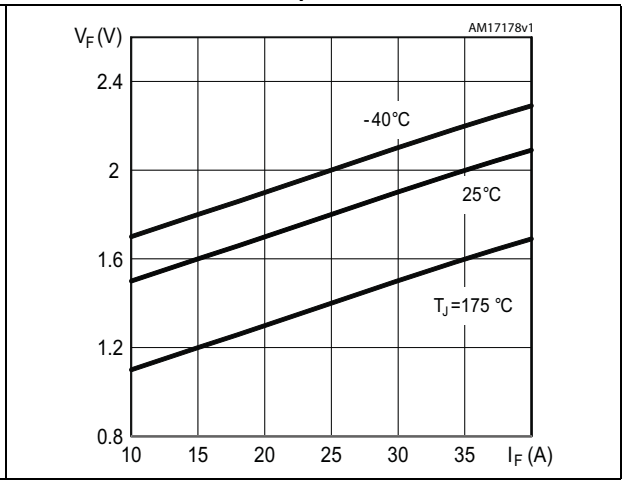


Figure 12. Normalized $V_{GE(th)}$ vs. junction temperature

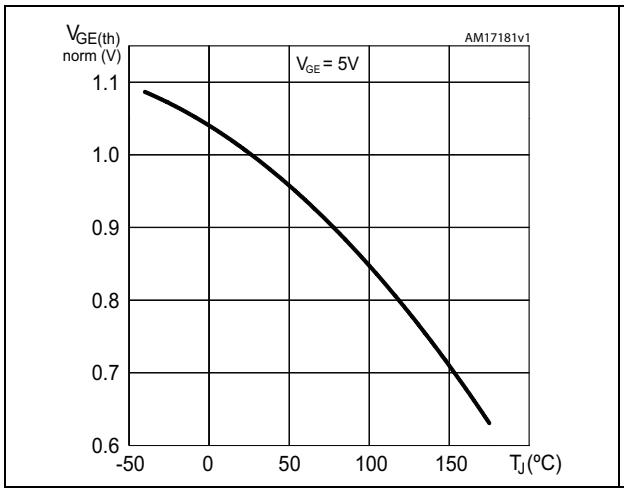


Figure 13. Normalized BV_{CES} vs. junction temperature

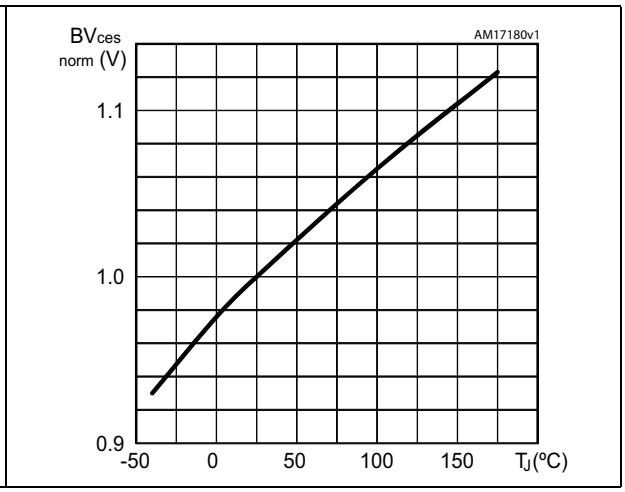


Figure 14. Capacitance variations

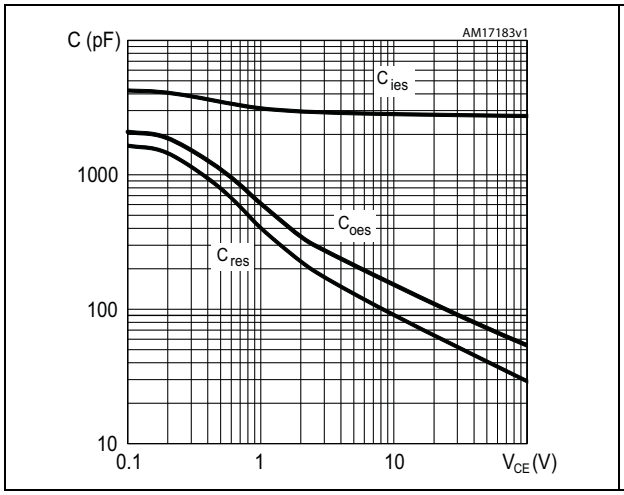


Figure 15. Gate charge vs. gate-emitter voltage

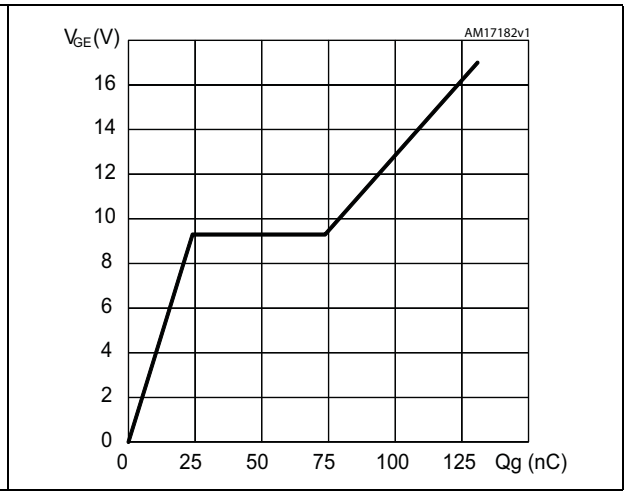


Figure 16. Switching losses vs. collector current

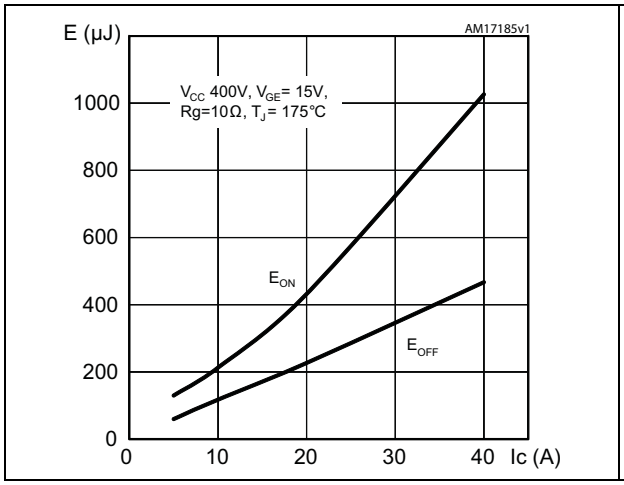


Figure 17. Switching losses vs. gate resistance

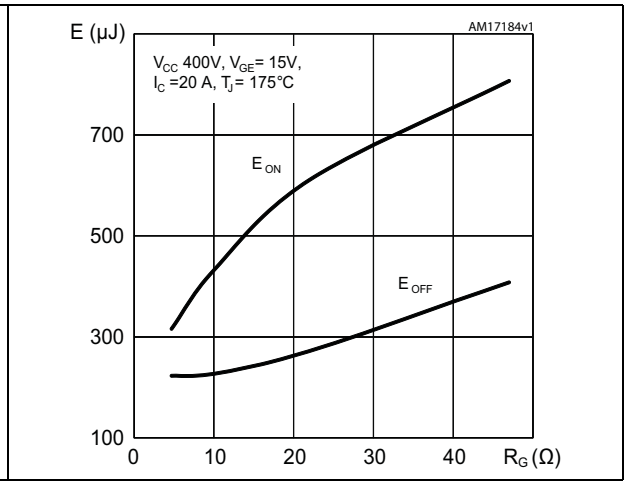


Figure 18. Switching losses vs. junction temperature

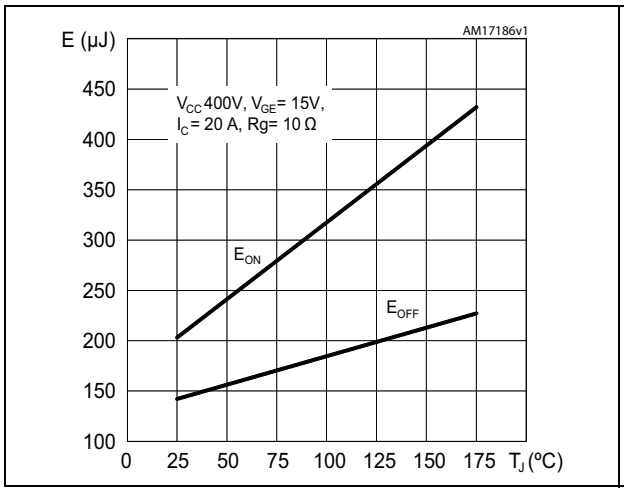


Figure 19. Switching losses vs. collector emitter voltage

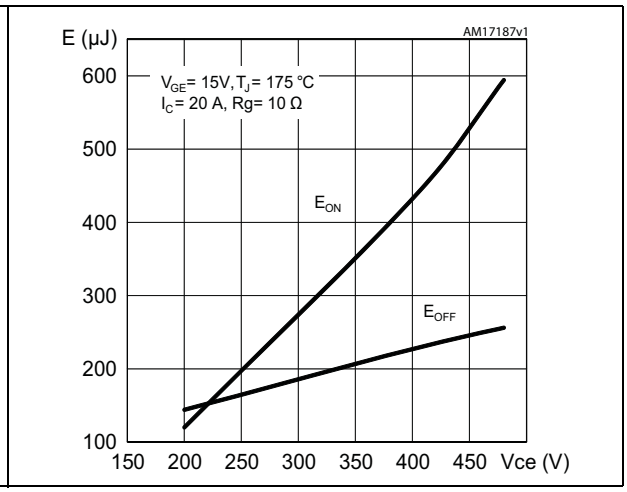


Figure 20. Switching times vs. collector current

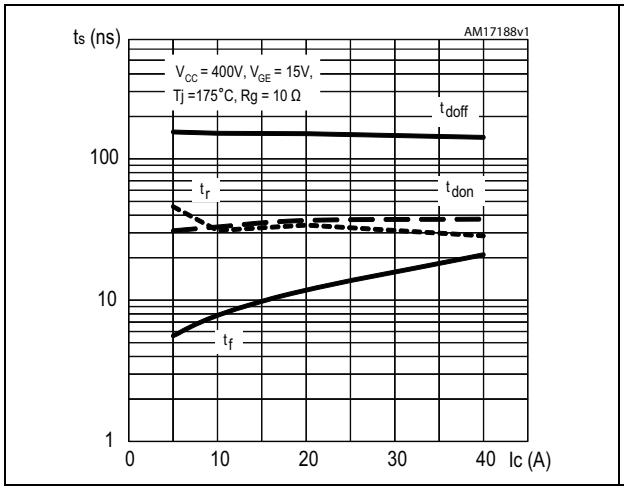


Figure 21. Switching times vs. gate resistance

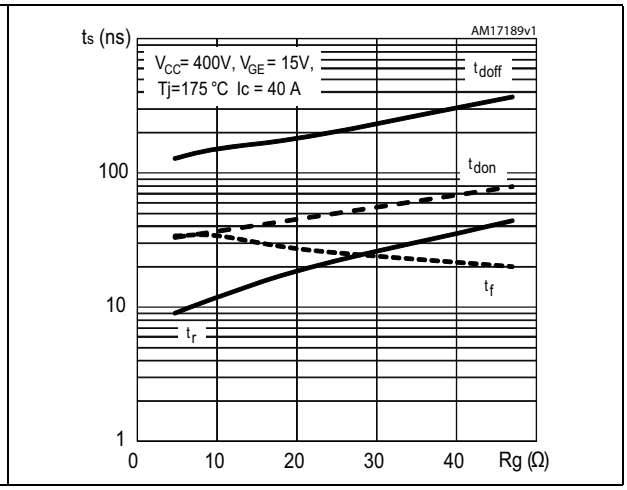


Figure 22. Reverse recovery current vs. diode current slope

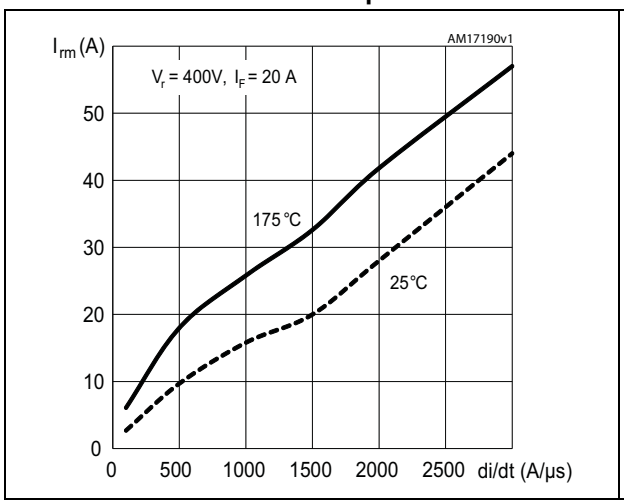


Figure 23. Reverse recovery time vs. diode current slope

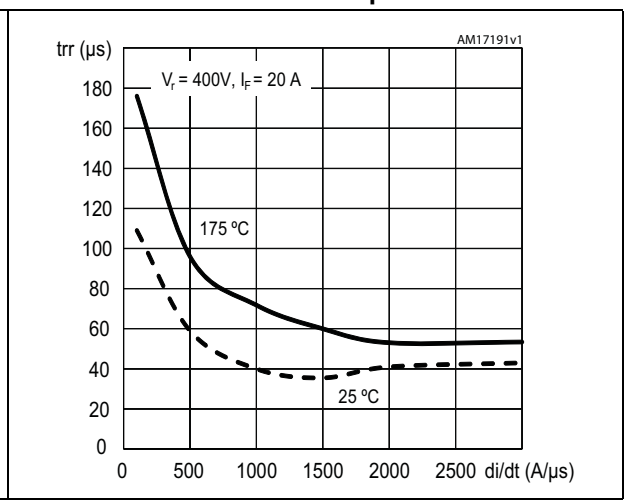


Figure 24. Reverse recovery charge vs. diode current slope

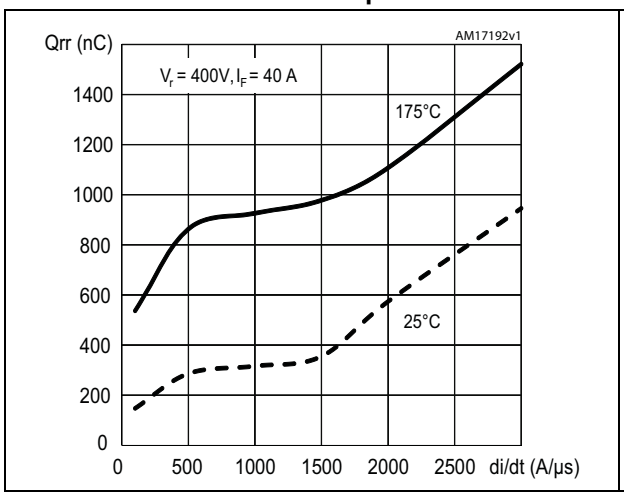


Figure 25. Reverse recovery energy vs. diode current slope

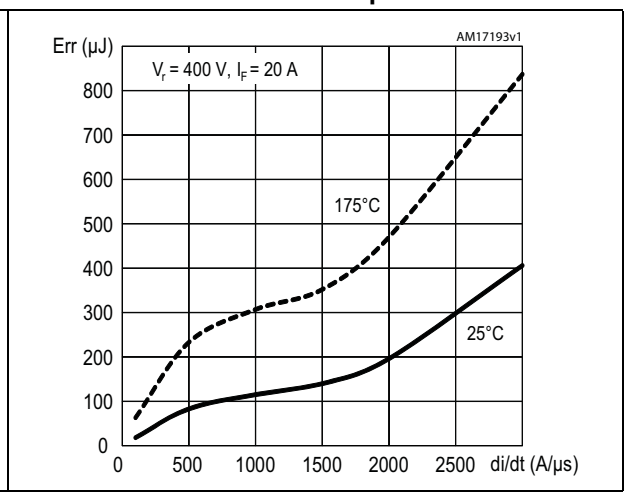


Figure 26. Thermal data for IGBT

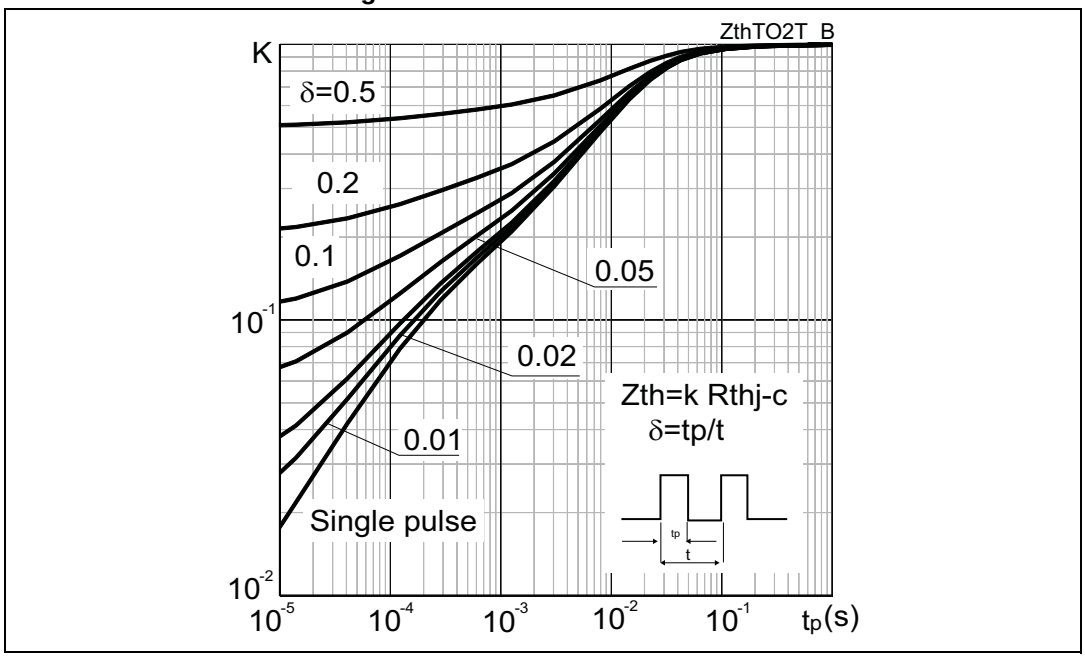
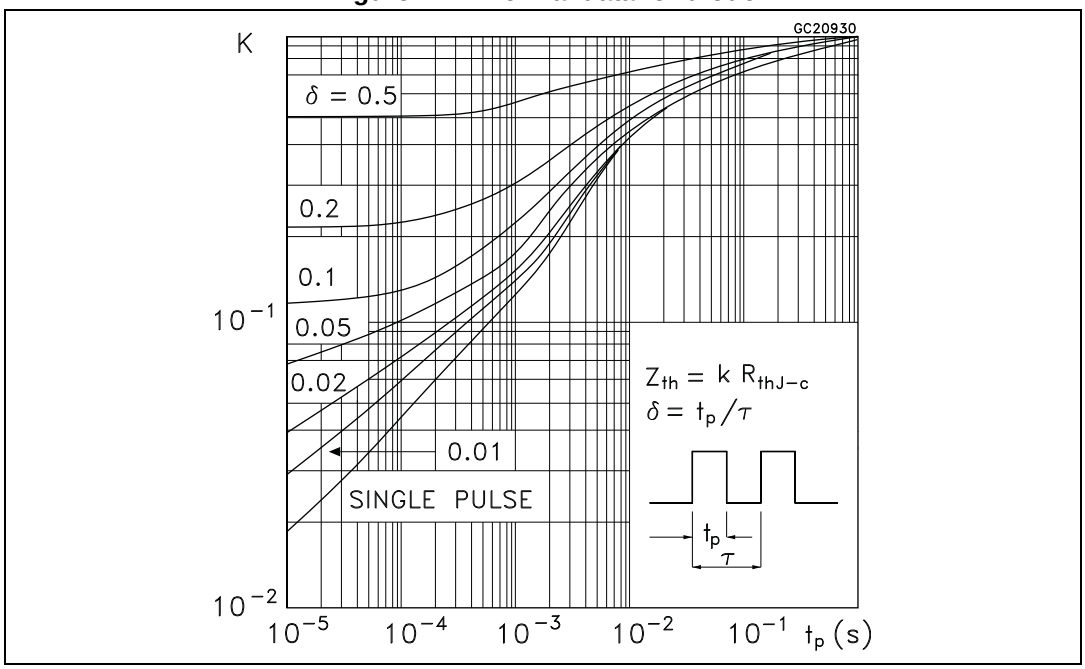


Figure 27. Thermal data for diode



3 Test circuits

Figure 28. Test circuit for inductive load switching

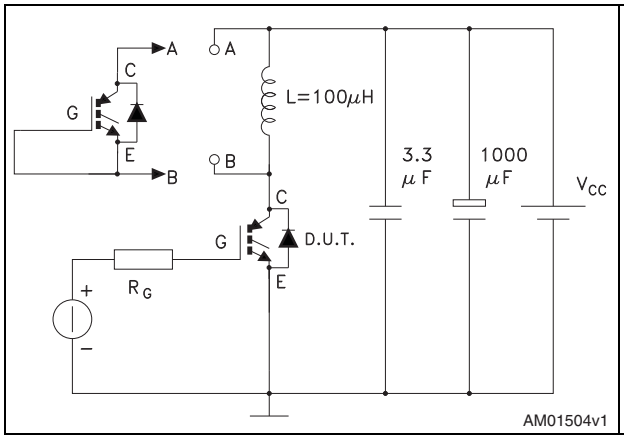


Figure 29. Gate charge test circuit

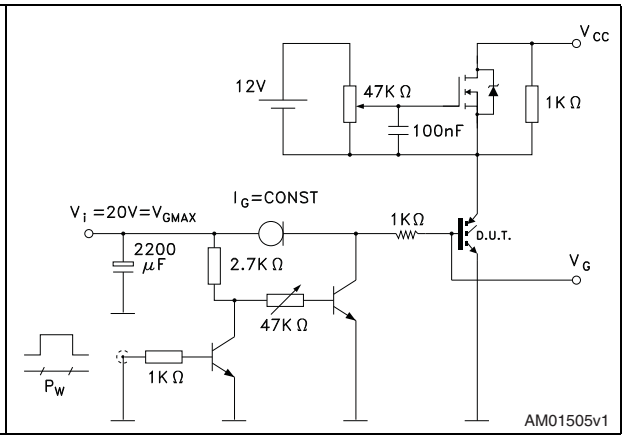


Figure 30. Switching waveform

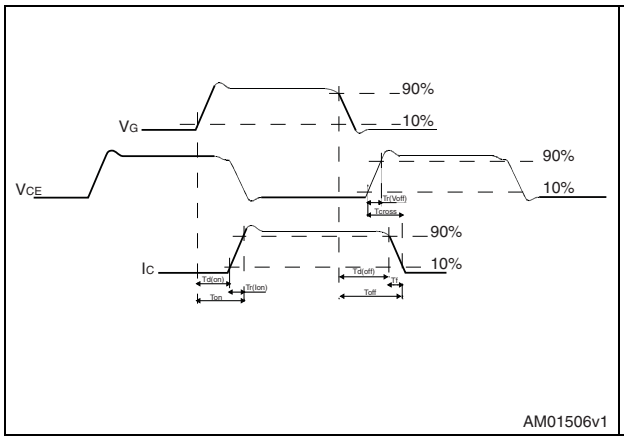
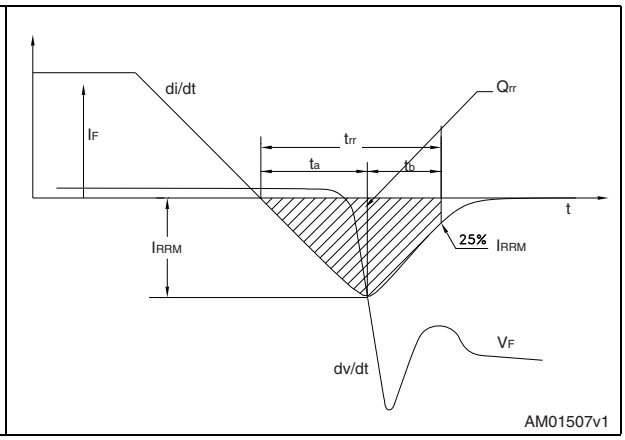


Figure 31. Diode recovery time waveform



4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

Table 8. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
∅P	3.75		3.85
Q	2.65		2.95

Figure 32. TO-220 type A drawing

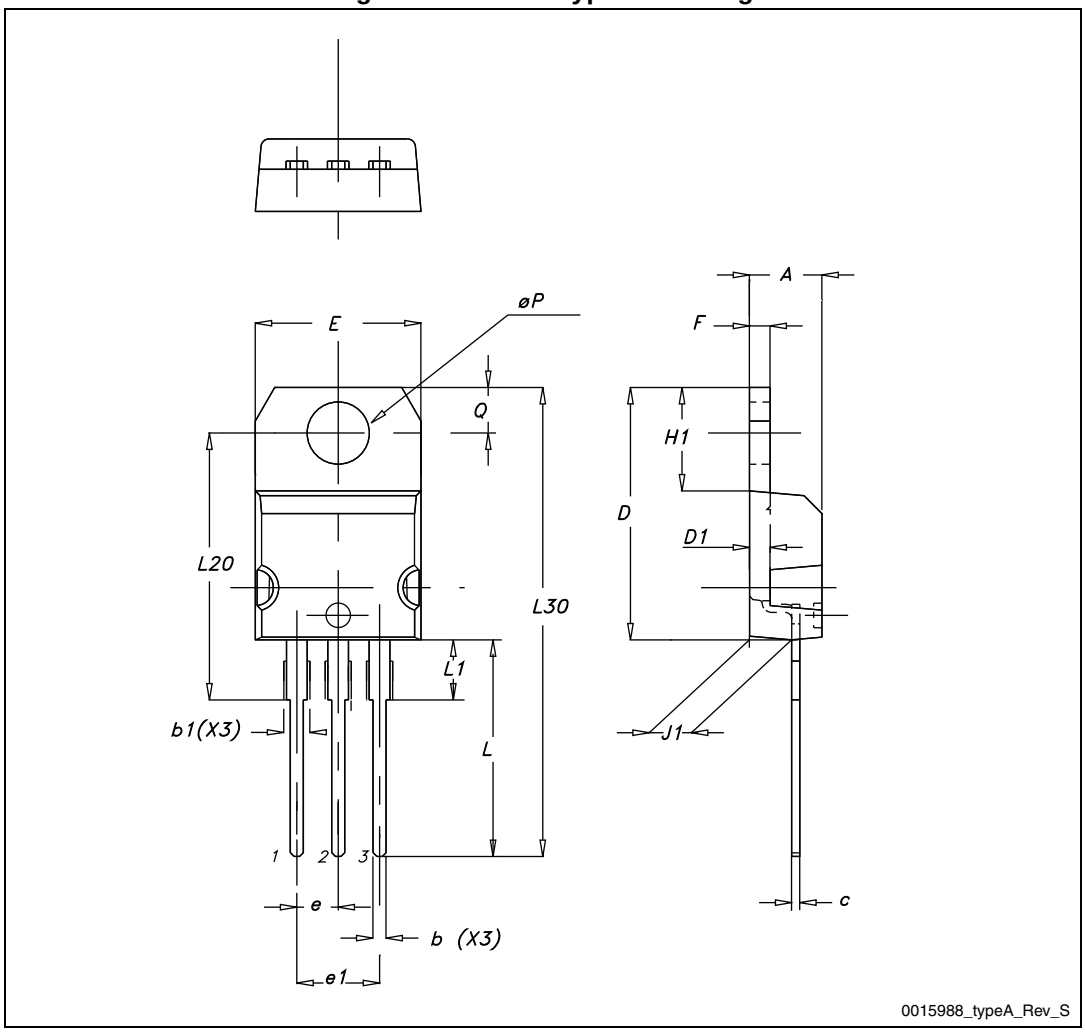


Table 9. D²PAK (TO-263) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50		
E	10		10.40
E1	8.50		
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 33. D²PAK (TO-263) drawing

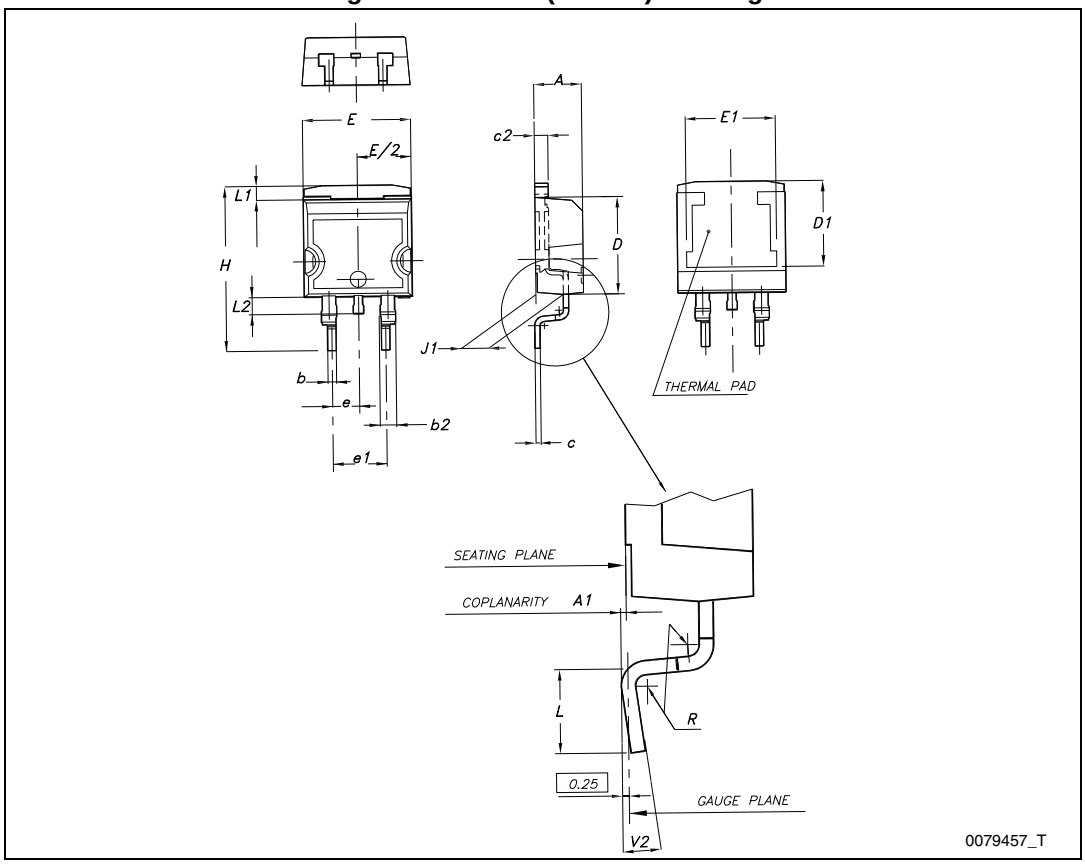
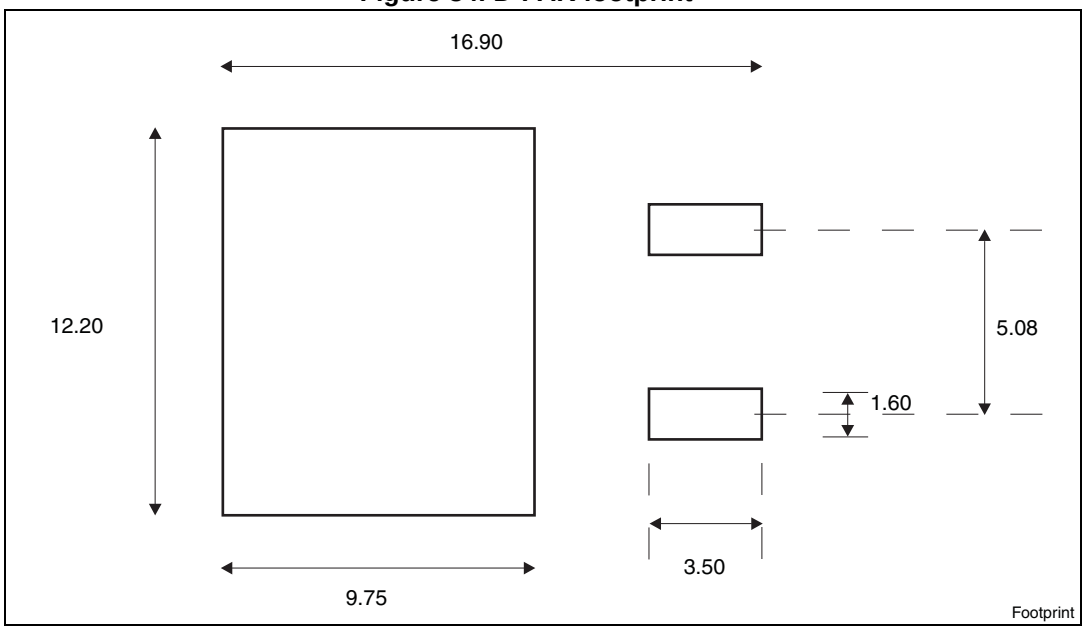


Figure 34. D²PAK footprint [(a)]



a. All dimension are in millimeters

Table 10. TO-247 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
∅P	3.55		3.65
∅R	4.50		5.50
S	5.30	5.50	5.70

Figure 35. TO-247 drawing

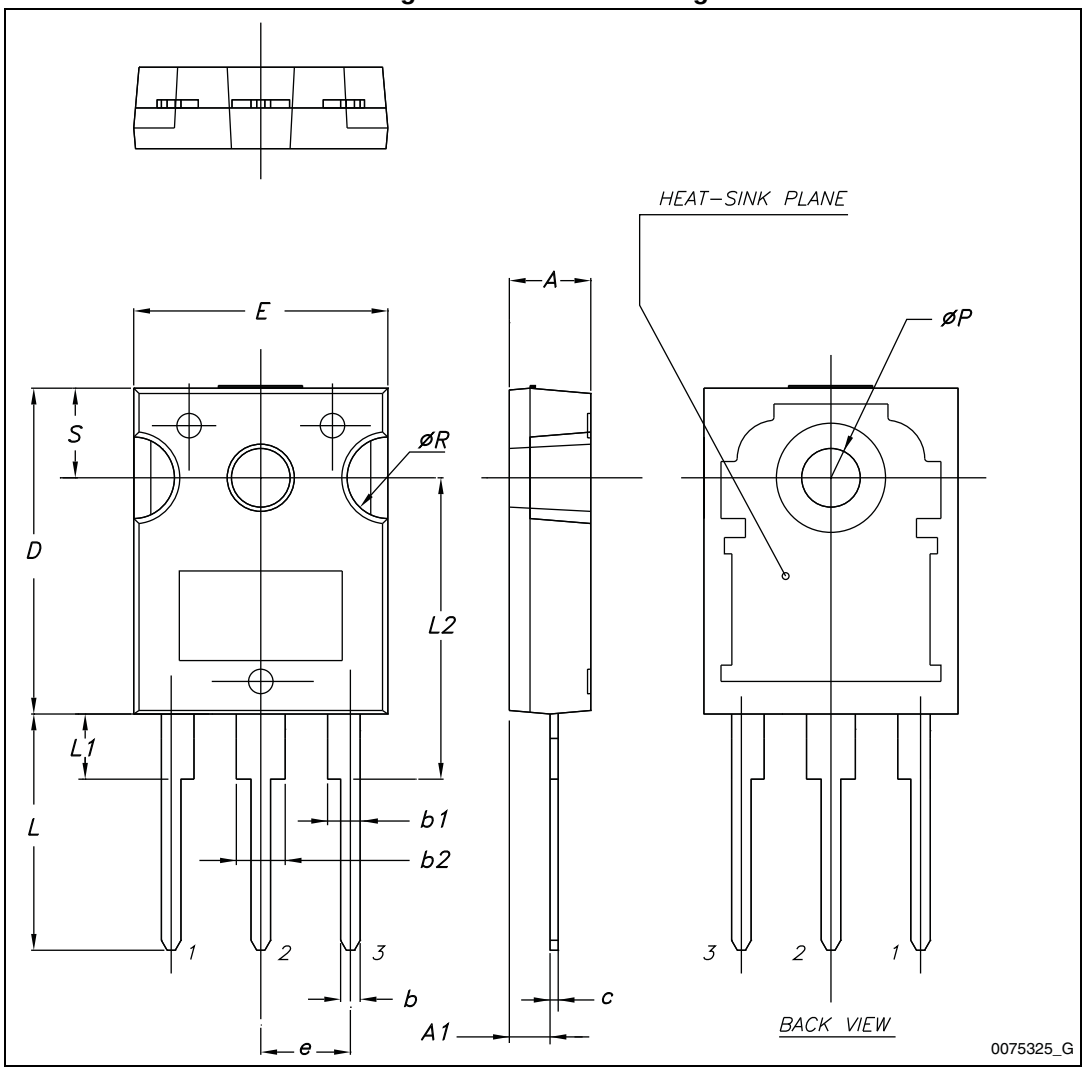
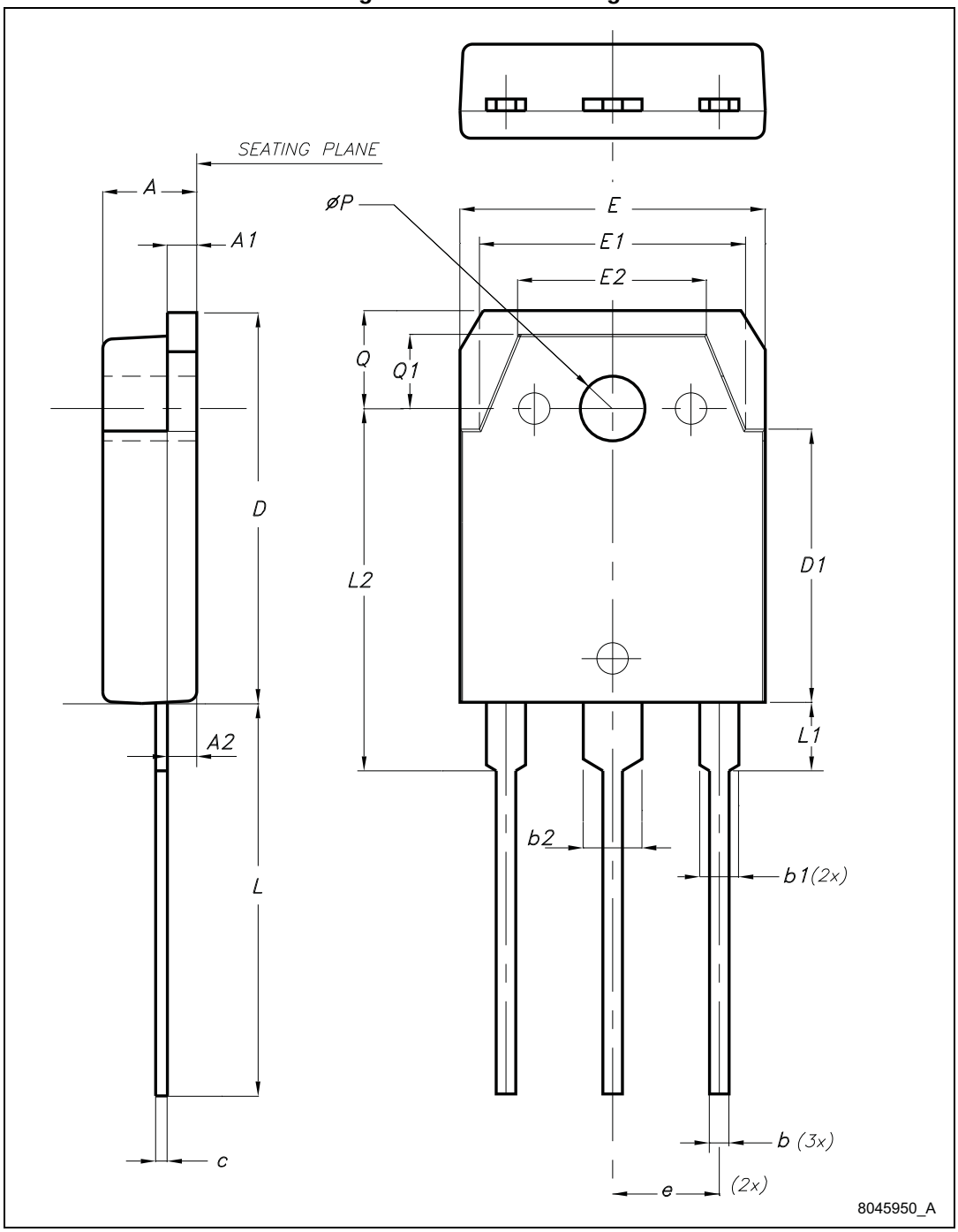


Table 11. TO-3P mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60		5
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1	1.20
b1	1.80		2.20
b2	2.80		3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1		13.90	
E	15.40		15.80
E1		13.60	
E2		9.60	
e	5.15	5.45	5.75
L	19.50	20	20.50
L1		3.50	
L2	18.20	18.40	18.60
øP	3.10		3.30
Q		5	
Q1		3.80	

Figure 36. TO-3P drawing



5 Packing mechanical data

Table 12. D²PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 37. Tape

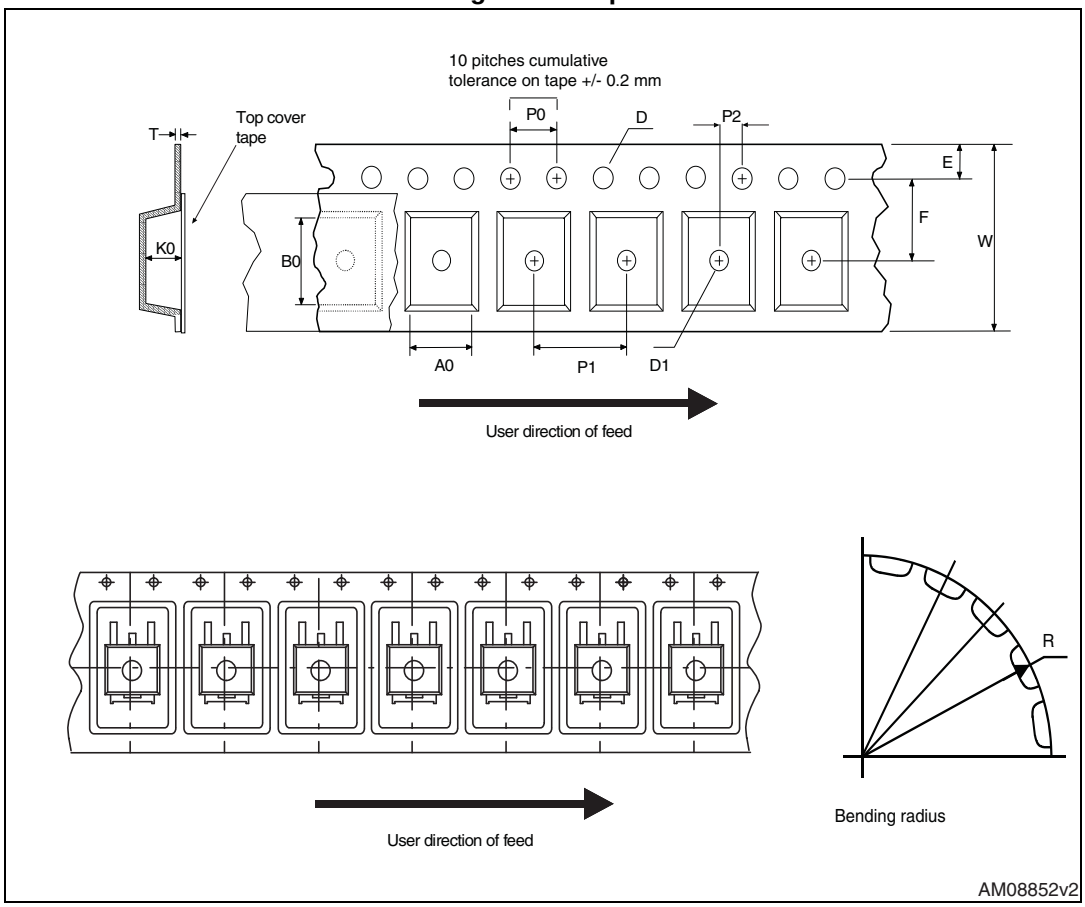
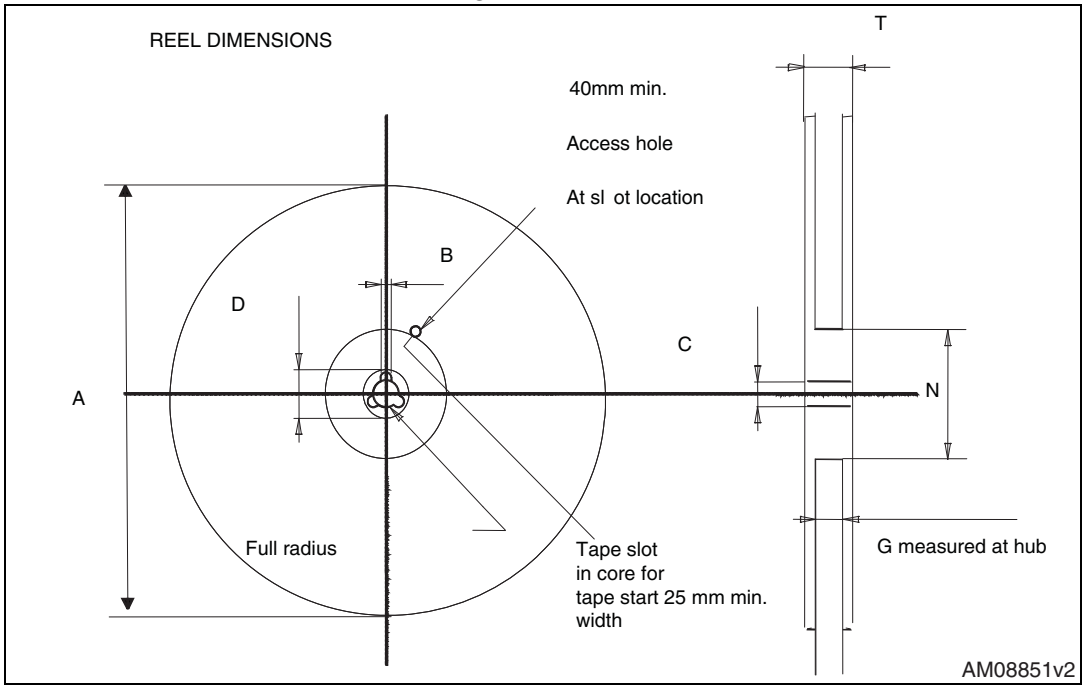


Figure 38. Reel



6 Revision history

Table 13. Document revision history

Date	Revision	Changes
12-Mar-2013	1	Initial release.
16-May-2013	2	Document status promoted from preliminary data to production data. Added: – New root part numbers STGB20V60DF and STGP20V60DF *Table 1 on page 1*. – Package mechanical data *Table 8 on page 12*, *Table 9 on page 14*, *Figure 32 on page 13* and *Figure 33 on page 15*. – *Section 2.1: Electrical characteristics (curves) on page 6*.
04-Jun-2013	3	Added maximum value for $V_{GE(th)}$ and V_F in *Table 4: Static characteristics*.

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